Ultra-thin module transforms ePassport and eID card production

Measuring just 200 µm - roughly four times the thickness of an average human hair - the MOB10 is an impressive 20% thinner than its predecessor, and is ideally suited for use in ultra-thin inlays for passport datapages and identity cards. It is the first ultrathin contactless module available in high volume, and supports polycarbonate technology and new security features, yet is compatible with the existing production infrastructure.

**KEY BENEFITS**
- Allows for additional security layers and features and is optimized for polycarbonate technology
- Protects the chip against mechanical and environmental stress and reverse engineering
- Ultra-thin and flexible inlays for passport datapage and eID cards
- Improved product quality and increased document durability
- Higher production efficiency
- Builds on proven MOB industry technology and ensures production handshake

**KEY FEATURES**
- Total package thickness: 200 µm
- Leadframe thickness: 35 µm
- Improved leadframe material with Ag plating
- Compatible with MOB4/6 production lines
- One process for all chips

**APPLICATIONS**
- ePassports
- National eID cards
- eHealth cards
- Citizen cards
- Resident permits
- eDriver’s licenses
- High-security physical / logical access
MINIATURIZATION AND PRODUCT QUALITY
Extensive testing has proven the robustness of the MOB10. The very high degree of resilience leads to higher end-product quality, by making the document less vulnerable to damage. For example, the MOB10 withstands the damage caused by
- Mechanical stress in the field and during production
- Micro-cracks that can be initiated in the naked flip chip
- Environmental stress like humidity, chemicals, solvents etc.
- Thermal stress
- Light and laser
- Attacks and reverse engineering

Furthermore, to support the evolution of biometric passports, which will move the contactless module from the cover to the data page, the demand for miniaturization increases. The MOB10 meets this demand by being the leading ultra-thin contactless module.

PRODUCT COMPATIBILITY
The MOB10 is designed to be compatible with existing production lines and can be integrated into current manufacturing processes without modifying or replacing the in-place setup. This helps manufacturers to keep the costs low, and makes it easier to transition to more advanced government documents.

The MOB10 is compatible with standard production steps, including punching from frame, pick and place, interconnecting to modules with thermocompression welding, conductive gluing or soldering, and laminating. And, because the MOB10 module can accommodate a number of different secure ICs, multiple designs can be supported without increasing production costs or slowing down the production line.

SOLUTION PRODUCTIVITY
With the MOB10, NXP enables ultra-thin inlays, eCovers, and eDatapages, and supports fast production ramp-up. The NXP offer includes the chip, an operating system, an applet suite, and middleware - all of which are Common Criteria certified and ICAO compliant. We also offer pre-personalization and initialization support, for maximum flexibility in every implementation.

MOB MODULE EVOLUTION
The MOB10 is the latest in NXP’s groundbreaking MOB series which has set the industry standard for contactless IC packages. As a pioneer in the area of miniaturization, we have introduced several generations of contactless chip modules, each thinner than the one before it.

The ultra-thin profile of the MOB10 makes it possible to accommodate new security features and still include the secure microcontroller and its antenna, without adding bulk. As an option, the MOB10 will be available in the MOA8 footprint, for an even smaller design.

NON-PERSONALIZED E-GOVERNMENT SOLUTIONS
With DPA Countermeasures functionality
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